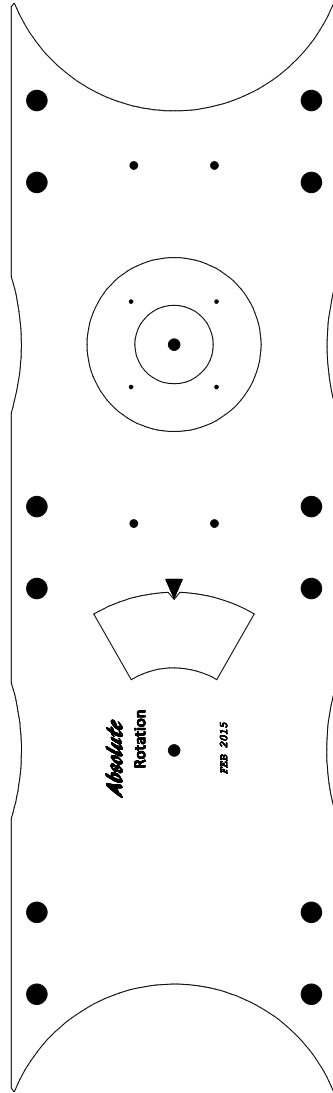
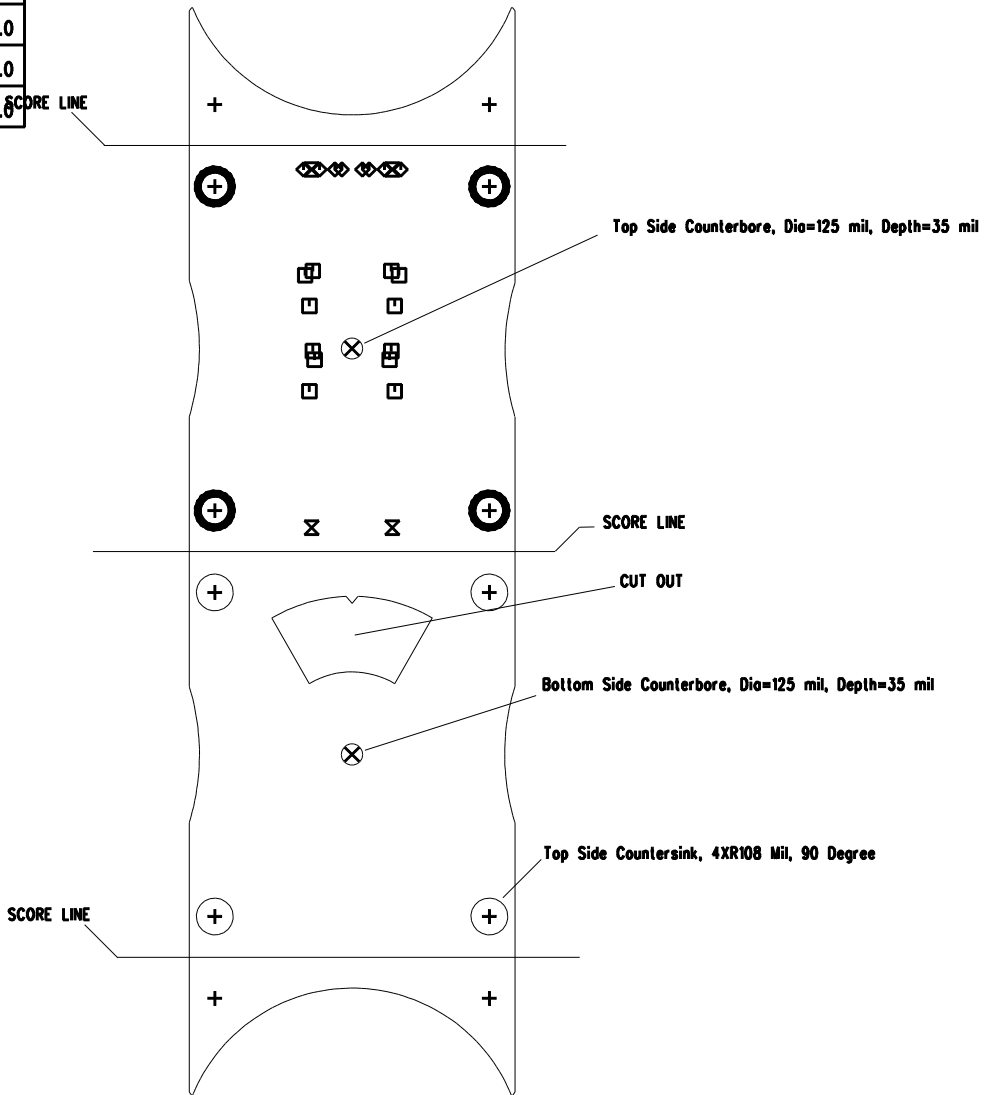


LAYER NAME	ASSEMBLY DRAWING TOP
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SIZE	QTY	SYM	PLATED	TOL
122	12	+	NO	+/-0.0
70	2	X	NO	+/-0.0
10	12	□	YES	+/-0.0
13	8	◇	YES	+/-0.0
47.24	4	⊗	NO	+/-0.0

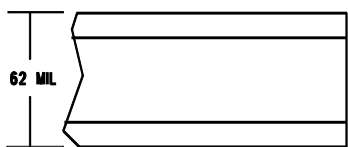


LAYER NAME	1	TDRILCOBROWING
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Overall Board Thickness: 62 Mil
 Soldermask Color: Red
 Silkscreen Color: White
 Drill hole tolerance: +/-3 Mil
 Copper/Spacing Clearances: 5/5 Mil

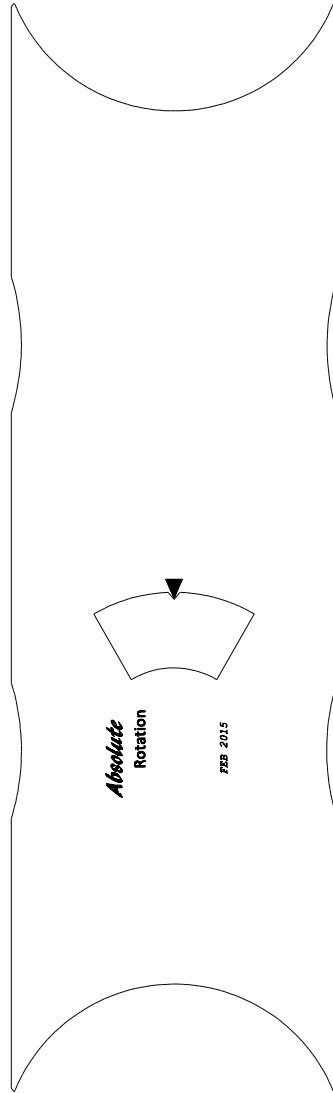
!! There are 3 score lines, 1 cut-out, 4 top countersinks, 1 top counterbore, 1 bottom counterbore !!

COMPANY	TI-SVA		
PCB PART NUMBER	COIL	REV	1
DATE	2/16/2015		
NOTES			

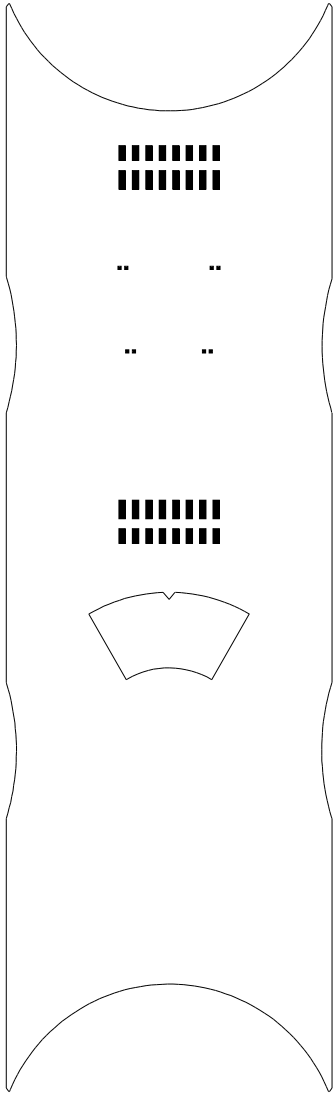


TOP: 1 OZ
 PREPREG
 INTERNAL1: 1 OZ
 37-40 MIL FR4
 INTERNAL2: 1 OZ
 PREPREG
 BOTTOM: 1 OZ

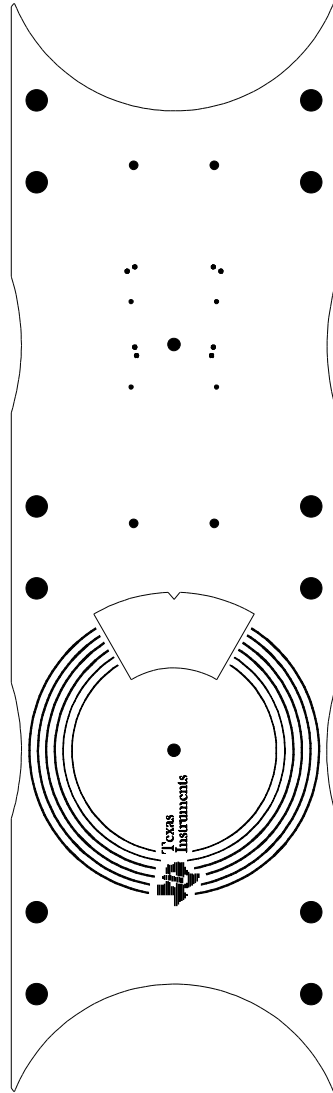
LAYER NAME	SILKSCREEN TOP
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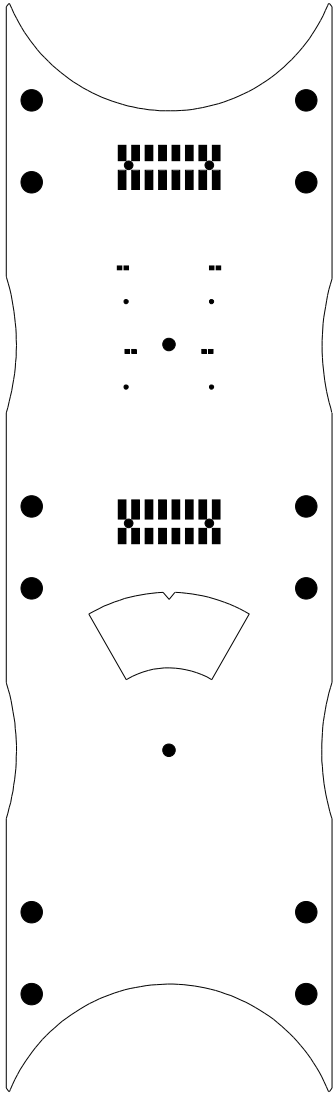
LAYER NAME	PASTE MASK BOTTOM
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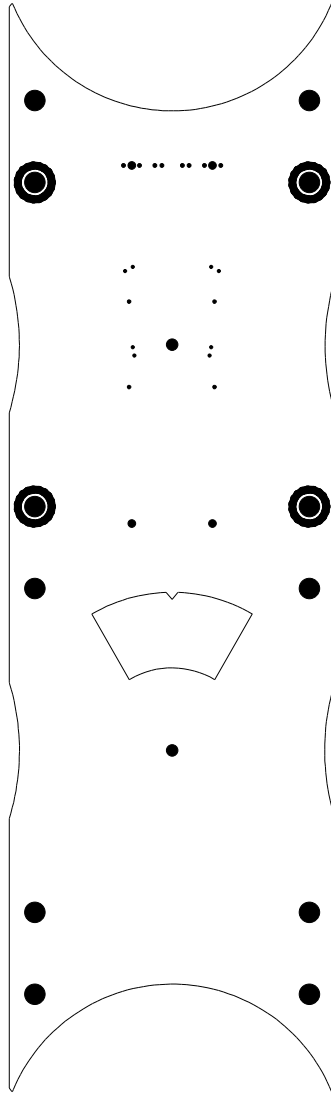
LAYER NAME	SOLDER MASK TOP
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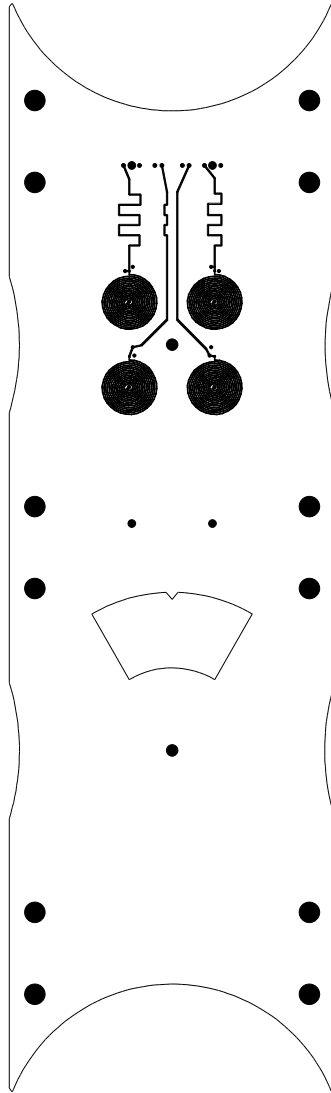
LAYER NAME	SOLDER MASK BOTTOM
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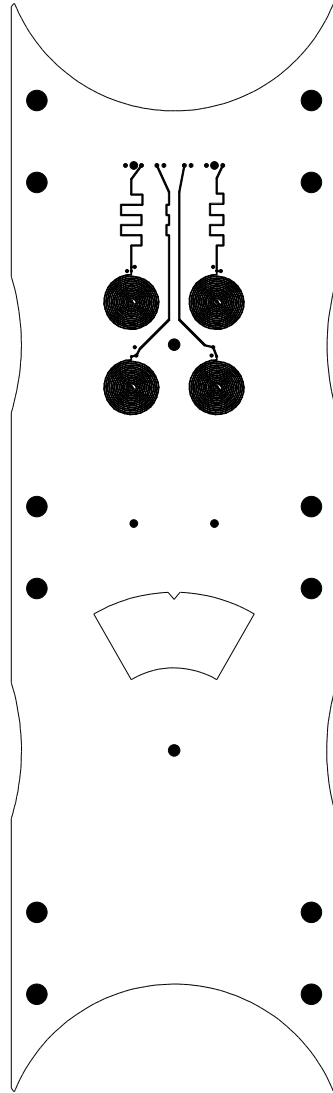
LAYER NAME	1	TOP COMPONENT
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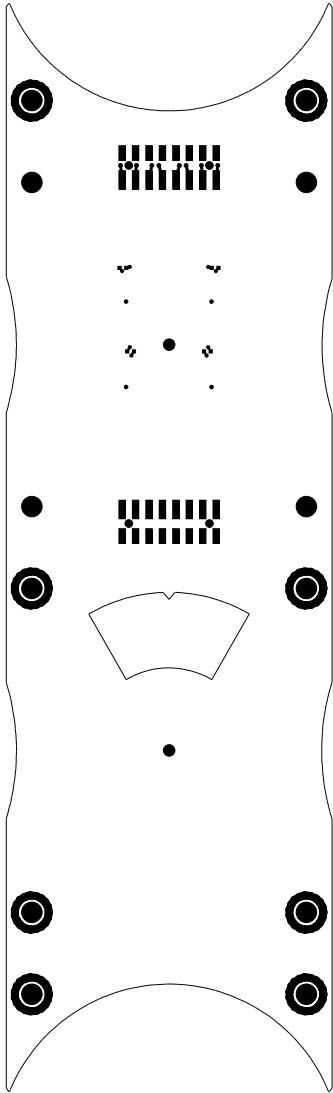
LAYER NAME	2	GROUND PLANE
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LAYER NAME	3	POWER POUR
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LAYER NAME	4	BOTTOM COMPONENT
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